TAIGITON

### GLASS PASSIVATED JUNCTION TRANSIENT VOLTAGE SUPPRESSOR

FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Fast reverse recovery time
- Lead free in comply with EU RoHS 2011/65/EU directives

SMAF

Dimensions in inches and (millimeters)

MECHANICAL DATA

- Case: SMAF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 27mg / 0.00095oz
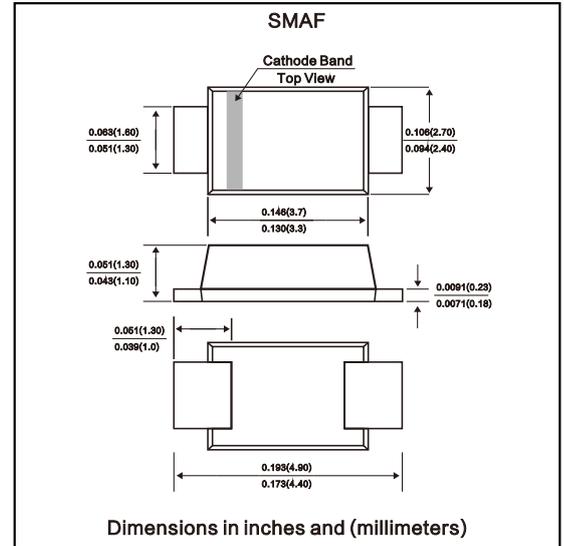
Absolute Maximum Ratings and Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

| Parameter	Symbols	RS3AF	RS3BF	RS3DF	RS3GF	RS3JF	RS3KF	RS3MF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at T_c = 125 °C	$I_{F(AV)}$	3							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	100							A
Maximum Forward Voltage at 3 A	V_F	1.3							V
Maximum DC Reverse Current T_a = 25 °C at Rated DC Blocking Voltage T_a =125 °C	I_R	5 100							µA
Typical Junction Capacitance at V_R=4V, f=1MHz	C_j	32							pF
Maximum Reverse Recovery Time [1]	t_{rr}	150				250	500		ns
Typical Thermal Resistance [2]	$R_{\theta JA}$ $R_{\theta JC}$	50 16							°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							°C

(1) Measured with I_F = 0.5 A, I_R = 1 A, I_{rr} = 0.25 A.

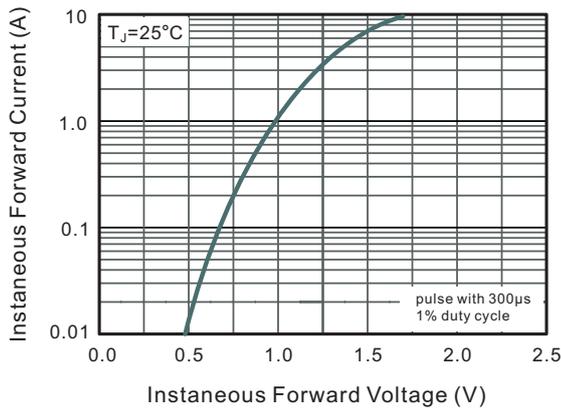(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

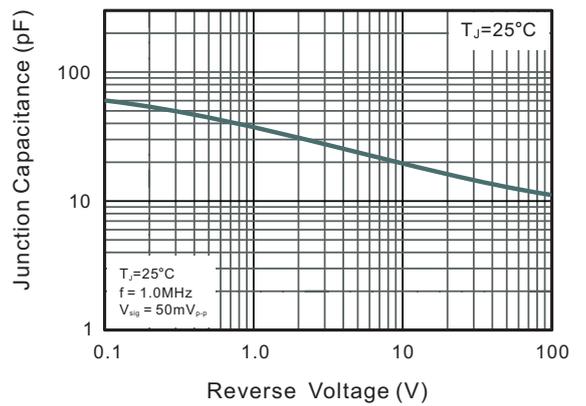### Fig.1 Maximum Average Forward Current Rating
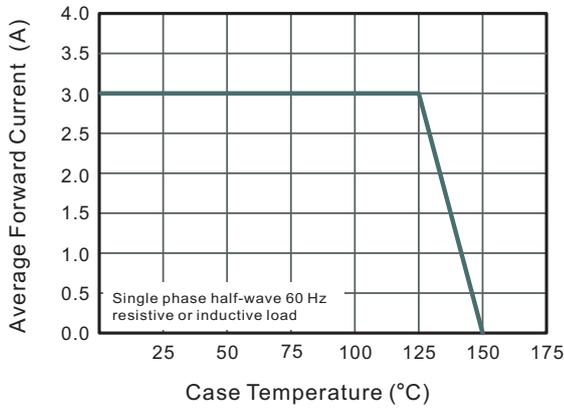
Fig.2 Typical Reverse Characteristics
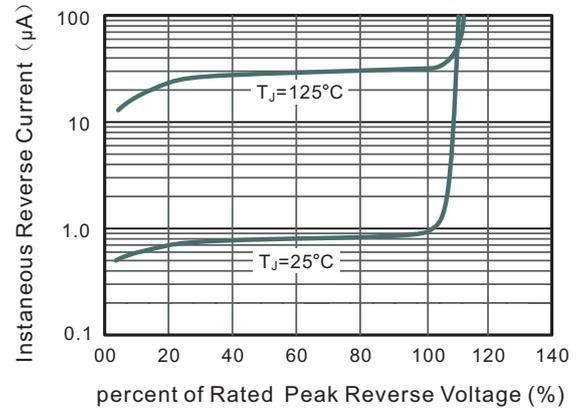
Fig.3 Typical Instaneous Forward Characteristics

Fig.4 Typical Junction Capacitance

Fig.5 Maximum Non-Repetitive Peak Forward Surage Current